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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	I <sup>2</sup> C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	124-VFTLA Dual Rows, Exposed Pad
Supplier Device Package	124-VTLA (9x9)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic32mx470f512lt-120-tl">https://www.e-xfl.com/product-detail/microchip-technology/pic32mx470f512lt-120-tl</a>

# PIC32MX330/350/370/430/450/470

**TABLE 6: PIN NAMES FOR 124-PIN DEVICES (CONTINUED)**

<b>124-PIN VTLA (BOTTOM VIEW)<sup>(1,2,3,4,5)</sup></b>  <b>PIC32MX330F064L</b> <b>PIC32MX350F128L</b> <b>PIC32MX350F256L</b> <b>PIC32MX370F512L</b>		A17  A1  Polarity Indicator		A34  Conductive Thermal Pad  A51  A68	
		B13		B29	
		B1		B41	
		B56			
Package Bump #	Full Pin Name		Package Bump #	Full Pin Name	
B7	MCLR		B32	SDA2/RA3	
B8	Vss		B33	TDO/RA5	
B9	TMS/CTED1/RA0		B34	OSC1/CLKI/RC12	
B10	RPE9/RE9		B35	No Connect	
B11	AN4/C1INB/RB4		B36	RPA14/RA14	
B12	Vss		B37	RPD8/RTCC/RD8	
B13	PGEC3/AN2/C2INB/RPB2/CTED13/RB2		B38	RPD10/PMCS2/RD10	
B14	PGED1/AN0/RPB0/RB0		B39	RPD0/RD0	
B15	No Connect		B40	SOSCO/RPC14/T1CK/RC14	
B16	PGED2/AN7/RPB7/CTED3/RB7		B41	Vss	
B17	VREF+/CVREF+/PMA6/RA10		B42	AN25/RPD2/RD2	
B18	AVss		B43	RPD12/PMD12/RD12	
B19	AN9/RPB9/CTED4/RB9		B44	RPD4/PMWR/RD4	
B20	AN11/PMA12/RB11		B45	PMD14/RD6	
B21	VDD		B46	No Connect	
B22	RPF13/RF13		B47	No Connect	
B23	AN12/PMA11/RB12		B48	VCAP	
B24	AN14/RPB14/CTED5/PMA1/RB14		B49	RPF0/PMD11/RF0	
B25	Vss		B50	RPG1/PMD9/RG1	
B26	RPD14/RD14		B51	TRCLK/RA6	
B27	RPF4/PMA9/RF4		B52	PMD0/RE0	
B28	No Connect		B53	VDD	
B29	RPF8/RF8		B54	TRD2/RG14	
B30	RPF6/SCKI/INT0/RF6		B55	TRD0/RG13	
B31	SCL1/RG2		B56	RPE3/CTPLS/PMD3/RE3	

- Note**
- 1: The RPN pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.
  - 2: Every I/O port pin (RAX-RGx), with the exception of RF6, can be used as a change notification pin (CNAX-CNGx). See **Section 12.0 "I/O Ports"** for more information.
  - 3: RPF6 (bump B30) and RPF7 (bump A37) are only remappable for input functions.
  - 4: Shaded package bumps are 5V tolerant.
  - 5: It is recommended that the user connect the printed circuit board (PCB) ground to the conductive thermal pad on the bottom of the package. And to not run non-Vss PCB traces under the conductive thermal pad on the same side of the PCB layout.

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**TABLE 1-1: PINOUT I/O DESCRIPTIONS**

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	124-pin VTLA			
AN0	16	25	B14	I	Analog	Analog input channels.
AN1	15	24	A15	I	Analog	
AN2	14	23	B13	I	Analog	
AN3	13	22	A13	I	Analog	
AN4	12	21	B11	I	Analog	
AN5	11	20	A12	I	Analog	
AN6	17	26	A20	I	Analog	
AN7	18	27	B16	I	Analog	
AN8	21	32	A23	I	Analog	
AN9	22	33	B19	I	Analog	
AN10	23	34	A24	I	Analog	
AN11	24	35	B20	I	Analog	
AN12	27	41	B23	I	Analog	
AN13	28	42	A28	I	Analog	
AN14	29	43	B24	I	Analog	
AN15	30	44	A29	I	Analog	
AN16	4	10	A7	I	Analog	
AN17	5	11	B6	I	Analog	
AN18	6	12	A8	I	Analog	
AN19	8	14	A9	I	Analog	
AN20	62	98	A66	I	Analog	
AN21	64	100	A67	I	Analog	
AN22	1	3	B2	I	Analog	
AN23	2	4	A4	I	Analog	
AN24	49	76	A52	I	Analog	
AN25	50	77	B42	I	Analog	
AN26	51	78	A53	I	Analog	
AN27	3	5	B3	I	Analog	
CLKI	39	63	B34	I	ST/CMOS	External clock source input. Always associated with OSC1 pin function.
CLKO	40	64	A42	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with the OSC2 pin function.
OSC1	39	63	B34	I	ST/CMOS	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	40	64	A42	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
SOSCI	47	73	A47	I	ST/CMOS	32.768 kHz low-power oscillator crystal input; CMOS otherwise.
SOSCO	48	74	B40	O	—	32.768 kHz low-power oscillator crystal output.

**Legend:** CMOS = CMOS compatible input or output  
ST = Schmitt Trigger input with CMOS levels  
TTL = TTL input buffer

Analog = Analog input  
O = Output

P = Power  
I = Input

**Note 1:** This pin is only available on devices without a USB module.  
**2:** This pin is only available on devices with a USB module.  
**3:** This pin is not available on 64-pin devices.

## 2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V<sub>IH</sub>) and input low (V<sub>IL</sub>) requirements.

Ensure that the “Communication Channel Select” (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- “Using MPLAB® ICD 3” (poster) DS50001765
- “MPLAB® ICD 3 Design Advisory” DS50001764
- “MPLAB® REAL ICE™ In-Circuit Debugger User’s Guide” DS50001616
- “Using MPLAB® REAL ICE™ Emulator” (poster) DS50001749

## 2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V<sub>IH</sub>) and input low (V<sub>IL</sub>) requirements.

## 2.7 Trace

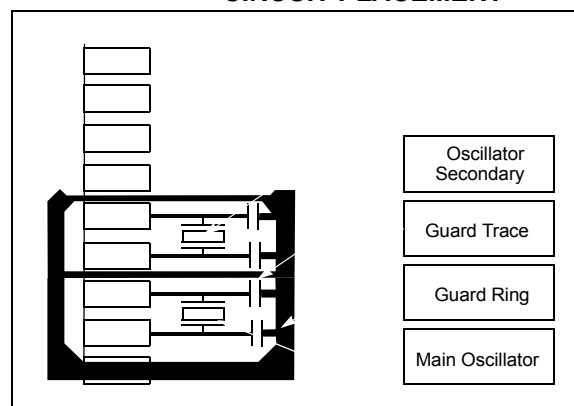
The trace pins can be connected to a hardware trace-enabled programmer to provide a compressed real-time instruction trace. When used for trace, the TRD3, TRD2, TRD1, TRD0 and TRCLK pins should be dedicated for this use. The trace hardware requires a 22 Ohm series resistor between the trace pins and the trace connector.

## 2.8 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 “Oscillator Configuration”** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

**FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT**



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## REGISTER 11-6: U1IR: USB INTERRUPT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R-0	R/WC-0, HS
	STALLIF	ATTACHIF <sup>(1)</sup>	RESUMEIF <sup>(2)</sup>	IDLEIF	TRNIF <sup>(3)</sup>	SOFIF	UERRIF <sup>(4)</sup>	URSTIF <sup>(5)</sup>
								DETACHIF <sup>(6)</sup>

<b>Legend:</b>	WC = Write '1' to clear	HS = Hardware Settable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared      x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **STALLIF:** STALL Handshake Interrupt bit

1 = In Host mode, a STALL handshake was received during the handshake phase of the transaction  
In Device mode, a STALL handshake was transmitted during the handshake phase of the transaction

0 = STALL handshake has not been sent

bit 6 **ATTACHIF:** Peripheral Attach Interrupt bit<sup>(1)</sup>

1 = Peripheral attachment was detected by the USB module

0 = Peripheral attachment was not detected

bit 5 **RESUMEIF:** Resume Interrupt bit<sup>(2)</sup>

1 = K-State is observed on the D+ or D- pin for 2.5  $\mu$ s

0 = K-State is not observed

bit 4 **IDLEIF:** Idle Detect Interrupt bit

1 = Idle condition detected (constant Idle state of 3 ms or more)

0 = No Idle condition detected

bit 3 **TRNIF:** Token Processing Complete Interrupt bit<sup>(3)</sup>

1 = Processing of current token is complete; a read of the U1STAT register will provide endpoint information

0 = Processing of current token not complete

bit 2 **SOFIF:** SOF Token Interrupt bit

1 = SOF token received by the peripheral or the SOF threshold reached by the host

0 = SOF token was not received nor threshold reached

bit 1 **UERRIF:** USB Error Condition Interrupt bit<sup>(4)</sup>

1 = Unmasked error condition has occurred

0 = Unmasked error condition has not occurred

bit 0 **URSTIF:** USB Reset Interrupt bit (Device mode)<sup>(5)</sup>

1 = Valid USB Reset has occurred

0 = No USB Reset has occurred

bit 0 **DETACHIF:** USB Detach Interrupt bit (Host mode)<sup>(6)</sup>

1 = Peripheral detachment was detected by the USB module

0 = Peripheral detachment was not detected

**Note 1:** This bit is valid only if the HOSTEN bit is set (see Register 11-11), there is no activity on the USB for 2.5  $\mu$ s, and the current bus state is not SE0.

**2:** When not in Suspend mode, this interrupt should be disabled.

**3:** Clearing this bit will cause the STAT FIFO to advance.

**4:** Only error conditions enabled through the U1EIE register will set this bit.

**5:** Device mode.

**6:** Host mode.

## 13.2 Control Registers

**TABLE 13-1: TIMER1 REGISTER MAP**

Virtual Address (BF80_#)	Register Name <sup>(1)</sup>	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
0600	T1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	TWDIS	TWIP	—	—	—	TGATE	—	TCKPS<1:0>		—	TSYNC	TCS	—	0000
0610	TMR1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR1<15:0>																0000
0620	PR1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR1<15:0>																FFFF

**Legend:** x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

**Note 1:** All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 “CLR, SET, and INV Registers”** for more information.

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**REGISTER 13-1: T1CON: TYPE A TIMER CONTROL REGISTER**

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R-0	U-0	U-0	U-0
	ON <sup>(1)</sup>	—	SIDL	TWDIS	TWIP	—	—	—
7:0	R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
	TGATE	—	TCKPS<1:0>		—	TSYNC	TCS	—

**Legend:**

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Timer On bit<sup>(1)</sup>

1 = Timer is enabled

0 = Timer is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit

1 = Discontinue operation when device enters Idle mode

0 = Continue operation even in Idle mode

bit 12 **TWDIS:** Asynchronous Timer Write Disable bit

1 = Writes to TMR1 are ignored until pending write operation completes

0 = Back-to-back writes are enabled (Legacy Asynchronous Timer functionality)

bit 11 **TWIP:** Asynchronous Timer Write in Progress bit

In Asynchronous Timer mode:

1 = Asynchronous write to TMR1 register in progress

0 = Asynchronous write to TMR1 register complete

In Synchronous Timer mode:

This bit is read as '0'.

bit 10-8 **Unimplemented:** Read as '0'

bit 7 **TGATE:** Timer Gated Time Accumulation Enable bit

When TCS = 1:

This bit is ignored.

When TCS = 0:

1 = Gated time accumulation is enabled

0 = Gated time accumulation is disabled

bit 6 **Unimplemented:** Read as '0'

bit 5-4 **TCKPS<1:0>:** Timer Input Clock Prescale Select bits

11 = 1:256 prescale value

10 = 1:64 prescale value

01 = 1:8 prescale value

00 = 1:1 prescale value

bit 3 **Unimplemented:** Read as '0'

**Note 1:** When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

## 15.1 Watchdog Timer Control Registers

**TABLE 15-1: WATCHDOG TIMER CONTROL REGISTER MAP**

Virtual Address (BF80_#)	Register Name <sup>(1)</sup>	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
0000	WDTCN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	—	—	—	—	—	—	SWDTPS<4:0>					WDTWINEN	WDTCLR	0000

**Legend:** x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

**Note 1:** All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 “CLR, SET, and INV Registers”** for more information.



## 16.0 INPUT CAPTURE

**Note:** This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 15. “Input Capture”** (DS60001122), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site ([www.microchip.com/pic32](http://www.microchip.com/pic32)).

The Input Capture module is useful in applications requiring frequency (period) and pulse measurement.

The Input Capture module captures the 16-bit or 32-bit value of the selected Time Base registers when an event occurs at the ICx pin. The following events cause capture events:

- Simple capture event modes:
  - Capture timer value on every falling edge of input at ICx pin
  - Capture timer value on every rising edge of input at ICx pin
  - Capture timer value on every edge (rising and falling)
  - Capture timer value on every edge (rising and falling), specified edge first.

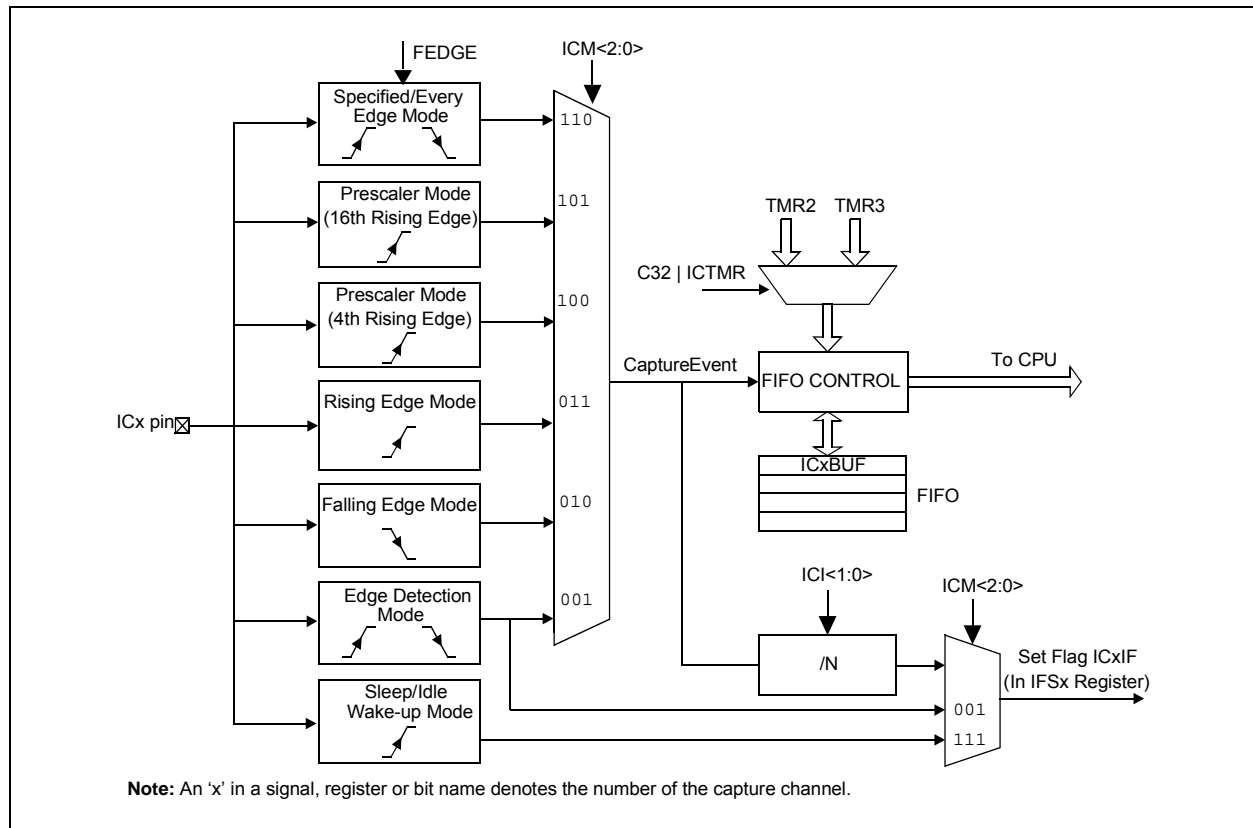
- Prescaler capture event modes:
  - Capture timer value on every 4th rising edge of input at ICx pin
  - Capture timer value on every 16th rising edge of input at ICx pin

Each input capture channel can select between one of two 16-bit timers (Timer2 or Timer3) for the time base, or two 16-bit timers (Timer2 and Timer3) together to form a 32-bit timer. The selected timer can use either an internal or external clock.

Other operational features include:

- Device wake-up from capture pin during CPU Sleep and Idle modes
- Interrupt on input capture event
- 4-word FIFO buffer for capture values  
Interrupt optionally generated after 1, 2, 3, or 4 buffer locations are filled
- Input capture can also be used to provide additional sources of external interrupts

**FIGURE 16-1: INPUT CAPTURE BLOCK DIAGRAM**



## 19.0 INTER-INTEGRATED CIRCUIT (I<sup>2</sup>C)

**Note:** This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 24. “Inter-Integrated Circuit (I<sup>2</sup>C)”** (DS60001116), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site ([www.microchip.com/pic32](http://www.microchip.com/pic32)).

The I<sup>2</sup>C module provides complete hardware support for both Slave and Multi-Master modes of the I<sup>2</sup>C serial communication standard. Figure 19-1 illustrates the I<sup>2</sup>C module block diagram.

Each I<sup>2</sup>C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I<sup>2</sup>C module offers the following key features:

- I<sup>2</sup>C interface supporting both master and slave operation
- I<sup>2</sup>C Slave mode supports 7-bit and 10-bit addressing
- I<sup>2</sup>C Master mode supports 7-bit and 10-bit addressing
- I<sup>2</sup>C port allows bidirectional transfers between master and slaves
- Serial clock synchronization for the I<sup>2</sup>C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I<sup>2</sup>C supports multi-master operation; detects bus collision and arbitrates accordingly
- Provides support for address bit masking

## REGISTER 19-1: I2CxCON: I<sup>2</sup>C CONTROL REGISTER (CONTINUED)

- bit 7     **GCEN:** General Call Enable bit (when operating as I<sup>2</sup>C slave)  
1 = Enable interrupt when a general call address is received in the I2CxRSR (module is enabled for reception)  
0 = General call address disabled
- bit 6     **STREN:** SCLx Clock Stretch Enable bit (when operating as I<sup>2</sup>C slave)  
Used in conjunction with SCLREL bit.  
1 = Enable software or receive clock stretching  
0 = Disable software or receive clock stretching
- bit 5     **ACKDT:** Acknowledge Data bit (when operating as I<sup>2</sup>C master, applicable during master receive)  
Value that is transmitted when the software initiates an Acknowledge sequence.  
1 = Send NACK during Acknowledge  
0 = Send ACK during Acknowledge
- bit 4     **ACKEN:** Acknowledge Sequence Enable bit  
(when operating as I<sup>2</sup>C master, applicable during master receive)  
1 = Initiate Acknowledge sequence on SDAx and SCLx pins and transmit ACKDT data bit.  
Hardware clear at end of master Acknowledge sequence.  
0 = Acknowledge sequence not in progress
- bit 3     **RCEN:** Receive Enable bit (when operating as I<sup>2</sup>C master)  
1 = Enables Receive mode for I<sup>2</sup>C. Hardware clear at end of eighth bit of master receive data byte.  
0 = Receive sequence not in progress
- bit 2     **PEN:** Stop Condition Enable bit (when operating as I<sup>2</sup>C master)  
1 = Initiate Stop condition on SDAx and SCLx pins. Hardware clear at end of master Stop sequence.  
0 = Stop condition not in progress
- bit 1     **RSEN:** Repeated Start Condition Enable bit (when operating as I<sup>2</sup>C master)  
1 = Initiate Repeated Start condition on SDAx and SCLx pins. Hardware clear at end of master Repeated Start sequence.  
0 = Repeated Start condition not in progress
- bit 0     **SEN:** Start Condition Enable bit (when operating as I<sup>2</sup>C master)  
1 = Initiate Start condition on SDAx and SCLx pins. Hardware clear at end of master Start sequence.  
0 = Start condition not in progress

**Note 1:** When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

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## REGISTER 21-1: PMCON: PARALLEL PORT CONTROL REGISTER (CONTINUED)

- bit 3 **CS1P**: Chip Select 0 Polarity bit<sup>(2)</sup>  
1 = Active-high ( $\overline{\text{PMCS1}}$ )  
0 = Active-low ( $\text{PMCS1}$ )
- bit 2 **Unimplemented**: Read as '0'
- bit 1 **WRSP**: Write Strobe Polarity bit  
For Slave Modes and Master mode 2 ( $\text{MODE}<1:0> = 00,01,10$ ):  
1 = Write strobe active-high ( $\overline{\text{PMWR}}$ )  
0 = Write strobe active-low ( $\text{PMWR}$ )  
For Master mode 1 ( $\text{MODE}<1:0> = 11$ ):  
1 = Enable strobe active-high ( $\text{PMENB}$ )  
0 = Enable strobe active-low ( $\overline{\text{PMENB}}$ )
- bit 0 **RDSP**: Read Strobe Polarity bit  
For Slave modes and Master mode 2 ( $\text{MODE}<1:0> = 00,01,10$ ):  
1 = Read Strobe active-high ( $\overline{\text{PMRD}}$ )  
0 = Read Strobe active-low ( $\text{PMRD}$ )  
For Master mode 1 ( $\text{MODE}<1:0> = 11$ ):  
1 = Read/write strobe active-high ( $\overline{\text{PMRD/PMWR}}$ )  
0 = Read/write strobe active-low ( $\text{PMRD/PMWR}$ )

**Note 1:** When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON control bit.

**2:** These bits have no effect when their corresponding pins are used as address lines.

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## REGISTER 21-2: PMMODE: PARALLEL PORT MODE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —
23:16	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —
15:8	R-0 BUSY	R/W-0 IRQM<1:0>	R/W-0 IRQM<1:0>	R/W-0 INCM<1:0>	R/W-0 INCM<1:0>	R/W-0 MODE16	R/W-0 MODE<1:0>	R/W-0 MODE<1:0>
7:0	R/W-0 WAITB<1:0> <sup>(1)</sup>	R/W-0 WAITB<1:0> <sup>(1)</sup>	R/W-0 WAITB<1:0> <sup>(1)</sup>	R/W-0 WAITM<3:0> <sup>(1)</sup>	R/W-0 WAITM<3:0> <sup>(1)</sup>	R/W-0 WAITM<3:0> <sup>(1)</sup>	R/W-0 WAITE<1:0> <sup>(1)</sup>	R/W-0 WAITE<1:0> <sup>(1)</sup>

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **BUSY:** Busy bit (Master mode only)

1 = Port is busy

0 = Port is not busy

bit 14-13 **IRQM<1:0>:** Interrupt Request Mode bits

11 = Reserved, do not use

10 = Interrupt generated when Read Buffer 3 is read or Write Buffer 3 is written (Buffered PSP mode) or on a read or write operation when PMA<1:0> = 11 (Addressable Slave mode only)

01 = Interrupt generated at the end of the read/write cycle

00 = No Interrupt generated

bit 12-11 **INCM<1:0>:** Increment Mode bits

11 = Slave mode read and write buffers auto-increment (MODE<1:0> = 00 only)

10 = Decrement ADDR<15:0> by 1 every read/write cycle<sup>(2)</sup>

01 = Increment ADDR<15:0> by 1 every read/write cycle<sup>(2)</sup>

00 = No increment or decrement of address

bit 10 **MODE16:** 8/16-bit Mode bit

1 = 16-bit mode: a read or write to the data register invokes a single 16-bit transfer

0 = 8-bit mode: a read or write to the data register invokes a single 8-bit transfer

bit 9-8 **MODE<1:0>:** Parallel Port Mode Select bits

11 = Master mode 1 (PMCSx, PMRD/PMWR, PMENB, PMA<x:0>, PMD<7:0> and PMD<8:15><sup>(3)</sup>)

10 = Master mode 2 (PMCSx, PMRD, PMWR, PMA<x:0>, PMD<7:0> and PMD<8:15><sup>(3)</sup>)

01 = Enhanced Slave mode, control signals (PMRD, PMWR, PMCS, PMD<7:0> and PMA<1:0>)

00 = Legacy Parallel Slave Port, control signals (PMRD, PMWR, PMCS and PMD<7:0>)

bit 7-6 **WAITB<1:0>:** Data Setup to Read/Write Strobe Wait States bits<sup>(1)</sup>

11 = Data wait of 4 TPB; multiplexed address phase of 4 TPB

10 = Data wait of 3 TPB; multiplexed address phase of 3 TPB

01 = Data wait of 2 TPB; multiplexed address phase of 2 TPB

00 = Data wait of 1 TPB; multiplexed address phase of 1 TPB (default)

**Note 1:** Whenever WAITM<3:0> = 0000, WAITB and WAITE bits are ignored and forced to 1 TPB cycle for a write operation; WAITB = 1 TPB cycle, WAITE = 0 TPB cycles for a read operation.

**2:** Address bits, A15 and A14, are not subject to automatic increment/decrement if configured as Chip Select CS2 and CS1.

**3:** These pins are active when MODE16 = 1 (16-bit mode).

## 23.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

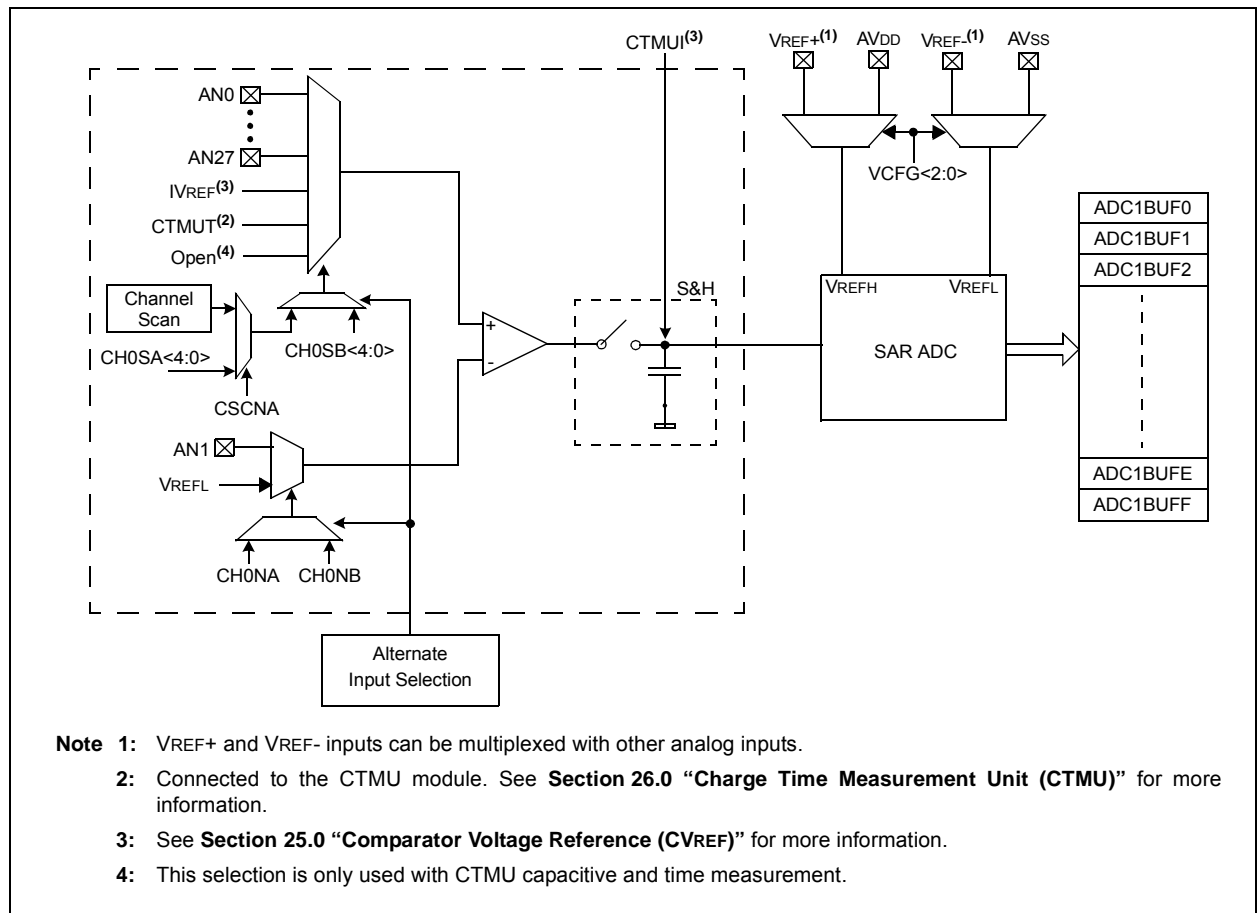
**Note:** This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 17. “10-bit Analog-to-Digital Converter (ADC)”** (DS60001104), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site ([www.microchip.com/pic32](http://www.microchip.com/pic32)).

The 10-bit Analog-to-Digital Converter (ADC) includes the following features:

- Successive Approximation Register (SAR) conversion
- Up to 1 Msps conversion speed
- Up to 28 analog input pins
- External voltage reference input pins
- One unipolar, differential Sample and Hold Amplifier (SHA)
- Automatic Channel Scan mode
- Selectable conversion trigger source
- 16-word conversion result buffer
- Selectable buffer fill modes
- Eight conversion result format options
- Operation during CPU Sleep and Idle modes

A block diagram of the 10-bit ADC is illustrated in Figure 23-1. The 10-bit ADC has up to 28 analog input pins, designated AN0-AN27. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins and may be common to other analog module references.

**FIGURE 23-1: ADC1 MODULE BLOCK DIAGRAM**



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## REGISTER 25-1: CVRCON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	ON(1)	—	—	—	—	—	—	—
7:0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	CVROE	CVRR	CVRSS	CVR<3:0>			

### Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Comparator Voltage Reference On bit<sup>(1)</sup>

1 = Module is enabled

Setting this bit does not affect other bits in the register.

0 = Module is disabled and does not consume current

Clearing this bit does not affect the other bits in the register.

bit 14-7 **Unimplemented:** Read as '0'

bit 6 **CVROE:** CVREFOUT Enable bit

1 = Voltage level is output on CVREFOUT pin

0 = Voltage level is disconnected from CVREFOUT pin

bit 5 **CVRR:** CVREF Range Selection bit

1 = 0 to 0.67 CVRSRC, with CVRSRC/24 step size

0 = 0.25 CVRSRC to 0.75 CVRSRC, with CVRSRC/32 step size

bit 4 **CVRSS:** CVREF Source Selection bit

1 = Comparator voltage reference source, CVRSRC = (VREF+) – (VREF-)

0 = Comparator voltage reference source, CVRSRC = AVDD – AVSS

bit 3-0 **CVR<3:0>:** CVREF Value Selection  $0 \leq \text{CVR}<3:0> \leq 15$  bits

When CVRR = 1:

$\text{CVREF} = (\text{CVR}<3:0>/24) \cdot (\text{CVRSRC})$

When CVRR = 0:

$\text{CVREF} = 1/4 \cdot (\text{CVRSRC}) + (\text{CVR}<3:0>/32) \cdot (\text{CVRSRC})$

**Note 1:** When using 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

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**REGISTER 28-1: DEVCFG0: DEVICE CONFIGURATION WORD 0**

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-0	r-1	r-1	R/P	r-1	r-1	r-1	R/P
	—	—	—	CP	—	—	—	BWP
23:16	r-1	r-1	r-1	r-1	R/P	R/P	R/P	R/P
	—	—	—	—	PWP<7:4>			
15:8	R/P	R/P	R/P	R/P	r-1	r-1	r-1	r-1
	PWP<3:0>				—	—	—	—
7:0	r-1	r-1	r-1	R/P	R/P	R/P	R/P	R/P
	—	—	—	ICESEL<1:0>		JTAGEN <sup>(1)</sup>	DEBUG<1:0>	

**Legend:**

R = Readable bit

-n = Value at POR

r = Reserved bit

W = Writable bit

'1' = Bit is set

P = Programmable bit

U = Unimplemented bit, read as '0'

'0' = Bit is cleared

x = Bit is unknown

bit 31 **Reserved:** Write '0'

bit 30-29 **Reserved:** Write '1'

bit 28 **CP:** Code-Protect bit

Prevents boot and program Flash memory from being read or modified by an external programming device.

1 = Protection is disabled

0 = Protection is enabled

bit 27-25 **Reserved:** Write '1'

bit 24 **BWP:** Boot Flash Write-Protect bit

Prevents boot Flash memory from being modified during code execution.

1 = Boot Flash is writable

0 = Boot Flash is not writable

bit 23-20 **Reserved:** Write '1'

bit 19-12 **PWP<7:0>:** Program Flash Write-Protect bits

Prevents selected program Flash memory pages from being modified during code execution. The PWP bits represent the one's complement of the number of write protected program Flash memory pages.

11111111 = Disabled

11111110 = 0xBD00\_0FFF

11111101 = 0xBD00\_1FFF

11111100 = 0xBD00\_2FFF

11111011 = 0xBD00\_3FFF

11111010 = 0xBD00\_4FFF

11111001 = 0xBD00\_5FFF

11111000 = 0xBD00\_6FFF

11110111 = 0xBD00\_7FFF

11110110 = 0xBD00\_8FFF

11110101 = 0xBD00\_9FFF

11110100 = 0xBD00\_AFFF

11110011 = 0xBD00\_BFFF

11110010 = 0xBD00\_CFFF

11110001 = 0xBD00\_DFFF

11110000 = 0xBD00\_EFFF

11101111 = 0xBD00\_FFFF

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01111111 = 0xBD07\_FFFF

**Note 1:** This bit sets the value for the JTAGEN bit in the CFGCON register.



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**REGISTER 28-6: DEVID: DEVICE AND REVISION ID REGISTER**

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	VER<3:0> <sup>(1)</sup>				DEVID<27:24> <sup>(1)</sup>			
23:16	R	R	R	R	R	R	R	R
	DEVID<23:16> <sup>(1)</sup>							
15:8	R	R	R	R	R	R	R	R
	DEVID<15:8> <sup>(1)</sup>							
7:0	R	R	R	R	R	R	R	R
	DEVID<7:0> <sup>(1)</sup>							

**Legend:**

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-28 **VER<3:0>**: Revision Identifier bits<sup>(1)</sup>

bit 27-0 **DEVID<27:0>**: Device ID<sup>(1)</sup>

**Note 1:** See the "PIC32 Flash Programming Specification" (DS60001145) for a list of Revision and Device ID values.

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## 30.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page ([www.microchip.com](http://www.microchip.com)) for the complete list of demonstration, development and evaluation kits.

## 30.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

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**TABLE 31-12: DC CHARACTERISTICS: PROGRAM MEMORY<sup>(3)</sup>**

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical <sup>(1)</sup>	Max.	Units	Conditions
D130	EP	Cell Endurance	20,000	—	—	E/W	—
D131	VPR	VDD for Read	2.3	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	2.3	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
D138	TWW	Word Write Cycle Time <sup>(4)</sup>	44	—	59	μs	—
D136	TRW	Row Write Cycle Time <sup>(2,4)</sup>	2.8	3.3	3.8	ms	—
D137	TPE	Page Erase Cycle Time <sup>(4)</sup>	22	—	29	ms	—
D139	TCE	Chip Erase Cycle Time <sup>(4)</sup>	86	—	116	ms	—

**Note 1:** Data in “Typical” column is at 3.3V, 25°C unless otherwise stated.

- 2:** The minimum SYSCLK for row programming is 8 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).
- 3:** Refer to the “PIC32 Flash Programming Specification” (DS60001145) for operating conditions during programming and erase cycles.
- 4:** This parameter depends on the FRC accuracy (see Table 31-20) and the FRC tuning values (see Register 8-2).

**TABLE 31-13: DC CHARACTERISTICS: PROGRAM FLASH MEMORY WAIT STATE**

DC CHARACTERISTICS		Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp	
Required Flash Wait States	SYSCLK	Units	Conditions
0 Wait State	0-40	MHz	-40°C to +85°C
	0-30	MHz	-40°C to +105°C
1 Wait State	41-80	MHz	-40°C to +85°C
	31-60	MHz	-40°C to +105°C
2 Wait States	81-100	MHz	-40°C to +85°C
	61-80	MHz	-40°C to +105°C
3 Wait States	101-120	MHz	0°C to +70°C

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**TABLE 31-36: 10-BIT CONVERSION RATE PARAMETERS**

AC CHARACTERISTICS <sup>(2)</sup>				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
ADC Input	ADC Speed	TAD Min.	Sampling Time Min.	Rs Max.	VDD	ADC Channels Configuration
AN0-AN14	1 Msps to 400 ksp <sup>(1)</sup>	65 ns	132 ns	500Ω	3.0V to 3.6V	
	Up to 400 ksp	200 ns	200 ns	5.0 kΩ	2.5V to 3.6V	
AN15-AN27	400 ksp <sup>(1)</sup>	154 ns	1000 ns	500Ω	3.0V to 3.6V	

**Note 1:** External VREF- and VREF+ pins must be used for correct operation.

**Note 2:** These parameters are characterized, but not tested in manufacturing.

## APPENDIX A: REVISION HISTORY

### Revision A (July 2012)

This is the initial released version of the document.

### Revision B (April 2013)

**Note:** The status of this data sheet was updated to Preliminary; however, any electrical specifications listed for PIC32MX370/470 devices is to be considered Advance Information and is marked accordingly.

This revision includes the following updates, as shown in Table A-1.

**TABLE A-1: MAJOR SECTION UPDATES**

Section	Update Description
<b>“32-bit Microcontrollers (up to 512 KB Flash and 128 KB SRAM) with Audio/Graphics/Touch (HMI), USB, and Advanced Analog”</b>	SRAM was changed from 32 KB to 64 KB. Data Memory (KB) was changed from 32 to 64 for the following devices (see Table 1): <ul style="list-style-type: none"><li>• PIC32MX350F256H</li><li>• PIC32MX350F256L</li><li>• PIC32MX450F256H</li><li>• PIC32MX450F256L</li></ul> The following devices were added: <ul style="list-style-type: none"><li>• PIC32MX370F512H</li><li>• PIC32MX370F512L</li><li>• PIC32MX470F512H</li><li>• PIC32MX470F512L</li></ul>
<b>4.0 “Memory Organization”</b>	The Memory Map for Devices with 256 KB of Program Memory was updated (see Figure 4-3). The Memory Map for Devices with 512 KB of Program Memory was added (see Figure 4-4).
<b>7.0 “Interrupt Controller”</b>	Updated the Interrupt IRQ, Vector and Bit Locations (see Table 7-1).
<b>20.0 “Parallel Master Port (PMP)”</b>	Added the CS2 bit and updated the ADDR bits in the Parallel Port Address register (see Register 20-3).
<b>27.0 “Special Features”</b>	Updated the PWP bit in the Device Configuration Word 3 register (see Register 27-4).
<b>30.0 “Electrical Characteristics”</b>	Note 2 in the DC Characteristics: Operating Current (IDD) were updated (see Table 30-5). Note 1 in the DC Characteristics: Idle Current (IDLE) were updated (see Table 30-6). Note 1 in the DC Characteristics: Power-down Current (IPD) were updated (see Table 30-7). Updated Program Memory values for parameters D135 (Tww), D136 (TRW), and D137 (TPE and TCE) (see Table 30-12).
<b>31.0 “DC and AC Device Characteristics Graphs”</b>	New IDD, IDLE, and IPD current graphs were added for PIC32MX330/430 devices and PIC32MX350/450 devices.